

Ultrasoft Recovery Bridge

Features

Ultrasoft recovery

low I_{RRM}

low VF

V_{RRM}

Special frame design for heat dissipation

Reduced EMI

Reduced snubbing

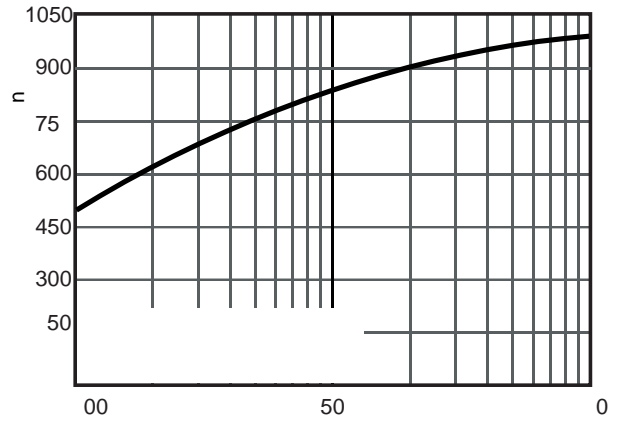
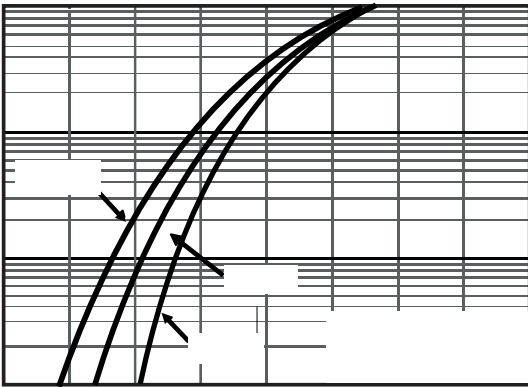
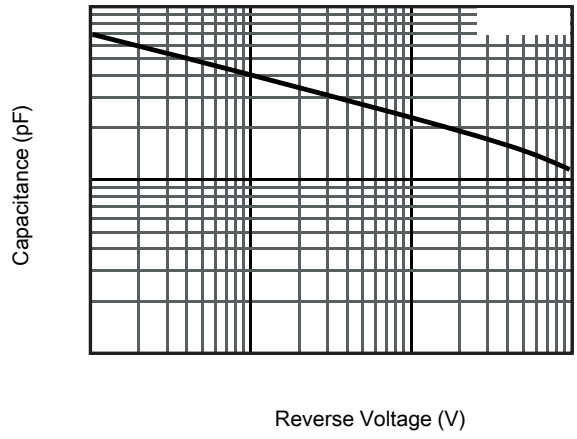
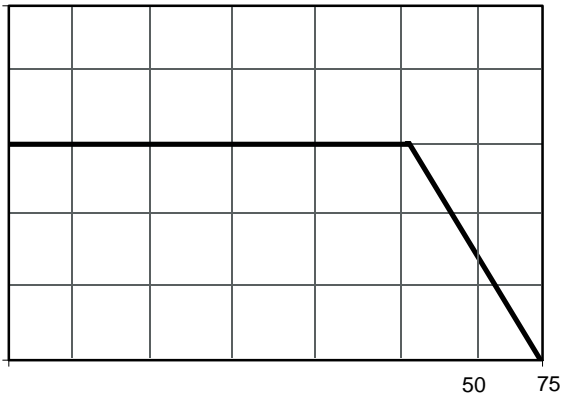
Input Pin (~)
Input Pin (~)
Output (+)
Output (-)

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		XBS30J	XBS30K	XBS30M	
			3		
Reverse Recovery Time:IF=0.5A,IR=1A,IRR=0.25A	T_{rr}		10		us
			1		
$I^2 t$ rating for fusing (F { • })	$I^2 t$				A ² S
1.5			0		
()			4		
			75		。
2			6 12		

Thermal resistance from Junction to case,lead and ambient in accordance with JESD-51.
Unit mounted on 15mm*12mm*1.6mm AL pad attach 195mm*195mm*10mm steel plate

RATINGS AND CHARACTERISTICS CURVES



PACKAGE OUTLINE DIMENSIONS

